Amendment to the Claims:

This listing of claims will replace all prior versions, listings of claims in the application:

Listing of Claims:

- 1-8 (Cancelled)
- 9. (Currently amended) A method to fabricate an organic electronic and opto-electronic device comprising
 - [Preparing] preparing a first part with at least a layer of a first organic material[[;]] containing a first polymerisable group
 - [Preparing] preparing a second part with at least a layer of a second organic material containing a second polymerisable group and subsequently contacting the first polymerisable group with the second polymerisable group
 - [Bonding] bonding said first part to said second part under an environment with controlled parameters, wherein said bonding of said first part and said second part is achieved by cross-linking between said first polymerisable group and said second polymerisable groups to form an active layer of an opto-electronic device.
- 10. (Currently amended) A method to fabricate an organic electronic and opto-electronic device as defined in [Claim] claim 9, wherein said first polymerisable group is the same as said second polymerisable group.
- 11. (Currently amended) A method to fabricate an organic electronic and opto-electronic device as defined in [Claim] claim 9, wherein said first polymerisable group is different from said second polymerisable group.

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12. (Currently amended) A method to fabricate an organic electronic and opto-electronic device as defined in [Claim] claim 9, wherein said first polymerisable group and said second polymerisable group are selected from a group of alkyl, acrylate, epoxy, vinyl, vinyl ether, oxethane, acrylnitrile, urethane, amino, hydroxyl, halide, isothiocynate, isocynate, nitrile, or a mixture of at least two of the above.

13. (Cancelled)

14. (Currently amended) A method to fabricate an organic electronic and opto-electronic device as defined in [Claim] claim 9, wherein said controlled parameters of said environment include heating, electron beam radiation or light lamination.